Client is in the semiconductor industry by developing strategic competencies, innovative technologies and intellectual property; enabling enterprises to be technologically competitive; and cultivating a technology talent pool to inject new knowledge to the industry.

## MICROSYSTEMS, MODULES & COMPONENTS LABORATORY

# Senior Research Engineer – MEMS Packaging

This position deals with wafer level hermetic/vacuum sealing and substrate level (first level) assembly required for MEMS packaging.

**Responsibilities:**

The key responsibility will includes development of wafer level encapsulation technology for MEMS devices, selection of materials for hermetic/vacuum sealing and first level over-molding for capped MEMS devices.

The candidate need to work with MEMS design team and electrical/mechanical modeling team to identify wafer level packaging schemes for different types of MEMS devices and to work with process team to develop packaging and assembly process.

The candidate also required to work with characterization and reliability test teams to characterize the packaged MEMS devices and study failure mechanism of the package.

**Requirements:**

- PhD degree in Mechanical engineering, Electrical Engineering with at least three years related experience
- Hands-on experience on wafer level MEMS packaging related works, including microfabrication process, wafer bonding with different material etc.
- Knowledge in MEMS design, electrical and mechanical modeling
- Excellent communication skills and teamwork with strong self-motivation

**Interested candidates are invited to submit your latest updated resume stating your availability of employment, current, achievements and expected salary to Adrian Collin Png at:** adrian@collincrawford.com

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